



687-788 SolderShield Device for StarShield™ Backshells

SolderShield device

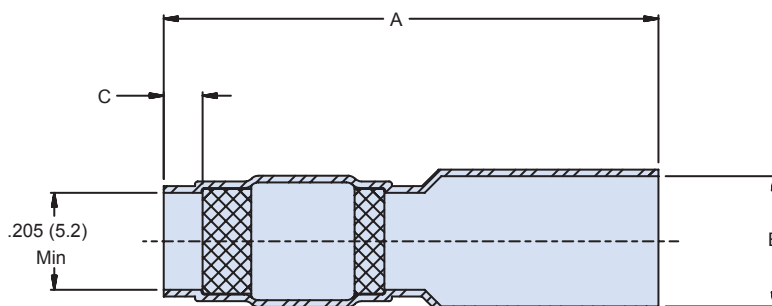
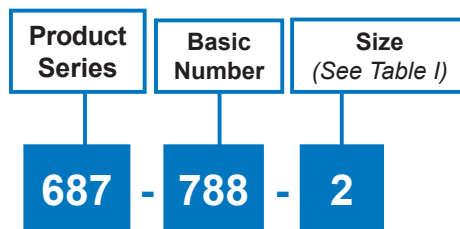


Table I

Size	A Dia Max	B Dia	C Max
02	1.045 (26.5)	.275 (7.00)	.080 (2.0)
04	1.181 (30.0)	.354 (9.00)	.098 (2.5)

Material/Finish:

Solder Shield Device:

Heat shrinkable insulation sleeve	Radiation cross-linked modified polyvinylidene fluoride
ArmorLite or Copper Braid	Pre-tinned with Sn9Ag3.5Cu.5 solder alloy with activated rosin flux
Solder Preform	Sn9Ag3.5Cu.5 solder alloy with mildly activated rosin flux

Notes:

1. Identified by bag and tag in suitable quantities.
2. The SolderShield Device is used on Glenair StarShield™ backshells.
3. Temperature range: -65°C to +175°C

Dimensions in inches (millimeters) and are subject to change without notice.